



Product Information

FELDER-ISO-Cream® "Clear", S-Pb93Sn5Ag2

Odourless no-clean solder paste for an excellent wetting on all well-known surfaces.

Metal powder content 88 % - 90 %, Pb93Sn5Ag2, DIN EN ISO 9453:2014

Flux, DIN EN 29454.1, 1.1.3.C, DIN EN 61190-1-3, RELO, IPC J-STD-004B, RELO

Item-No. : 23065200....

All information about our products is the result of our long standing experience which we would like to pass on to our customers as application support. However, as we do not have any influence on the application of the works carried out with our products, please see the warranty claims in our conditions of sale because our liability is limited.

This product information does not constitute warranted properties.

Description

The solder paste FELDER ISO-Cream® "Clear" is a homogenous, ready-made, odourless mixture of metal powder, binding agents, solvents, fluxes as well as thixotropic agents.

This paste has excellent wetting properties and is ideally suited for the soldering of difficult to solder areas. It is possible to use PCBs and components of different kind – the solder result is always optimal. The flux residues show a very high surface resistance.

The solder paste ISO-Cream® "Clear" is insensitive to humidity and temperature. It shows no tendencies to formation of solder balling on chip-resistors and capacitors.

FELDER-ISO-Cream® "Clear" has a very strong wet bonding force and is also suitable for assembly machines with very high accelerations/decelerations. The paste has a very long stencil time and can be used in printing machines with a temperature control unit (very strong ventilation). The rheology of this paste has been optimized to achieve excellent printing results on narrow openings as well as a very good first print after a break. Laboratory tests have shown that the first print after a break of 6 hours was unobjectionable. FELDER-ISO-Cream® "Clear" " is excellently suitable for vapour phase applications.

Properties

Alloy	DIN EN ISO 9453	Melting point	Metal powder content	Viscosity*
Pb93Sn5Ag2	Pb93Sn5Ag2	296 - 301° C	88 - 90 %	300.000 - 900.000 mPas

* Viscosity measured with Brookfield RVT, Shaft TF 5 U/min, 25° C

Grain sizes: 3 = Fine-Pitch 25 - 45 µm

Powder form: ball-shaped

Flux: DIN EN 29454.1, 1.1.3.C, DIN EN 61190-1-3, RELO, IPC J-STD-004B, RELO

Stencil strength: Standard = 150 – 200 µm
 Fine-Pitch = 100 – 150 µm
 Super Fine-Pitch = 80 – 125 µm

Organic Carrier Materials

The composition of **FELDER ISO-Cream® "Clear"** solder paste largely excludes an encrustation when stocked properly and assures the following rheological properties:

- excellent printability
- constant viscosity

Advantages

- colourless flux residues
- little content of volatiles ⇒ longer cleaning intervals of the reflow oven
- real no-clean quality
- excellent printing quality ⇒ high stencil time of at least 48 hours
- unobjectionable soldering results with all common soldering profiles
- insensitive to environmental influences
- stability of the viscosity also on print breaks
- ideally suitable for vapour phase soldering

Application Information

- Before opening the container, the paste should have reached room temperature, so that there will be no condensation on the paste.
- Stir **FELDER-ISO-Cream® "Clear"** well before use.
- **FELDER-ISO-Cream® "Clear"** keeps its adhesive consistency for a long period which allows trouble-free assembly of the circuit even after 48 hours. The exact period depends on the ambient conditions, size and form of the components as well as on the accelerations / decelerations on the line.
- The peak temperature depends on the thermal capacity of the components. On request we can provide you with our recommended solder profile.
- **FELDER-ISO-Cream® "Clear"** can be soldered under air or inert gas.
- Used solder paste (e.g. rest on the stencil) should not be replaced into the jar because the durability of the unused paste will be reduced essentially. Used solder paste should be kept separately and if necessary should be mixed with fresh solder paste directly before use.

Washing

Since the paste reaches the highest "no-clean level", the flux residues can remain on the soldered circuits and do not have to be washed away. Nevertheless, the residues can be removed in conventional washing plants.

Storage Advices

Store in tightly closed containers protected from humidity, sunlight and heat. FELDER-ISO-Cream® "Clear" can be stocked at least 6 months (storage at constant temperature of 5 - 15° C).

Delivery Forms

Jars:	0,250 and 0,500 kg
Cartridges:	6 and 12 oz Semco®
Cassettes:	ProFlow™
Dispensing cartridges:	5, 10 and 30 cc